

800V Super-junction Power MOSFET

Description

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Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The Multi-EPI SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

 Features Very low FOM R_{DS(on)}×Q_g 100% avalanche tested Easy to use/drive 		Uninterruptible PPower Factor Co	 Switch Mode Power Supply (SMPS) Uninterruptible Power Supply (UPS) Power Factor Correction (PFC) 			
• RoHS compliant TO-252	TO-251	• Low Power Chargers and Adapters				
Device Marking and Package Information						
Device	Package		Marking			
TPD80R900M	TO-252		80R900M			
TPU80R900M	TO-251		80R900M			
Key Performance Pa	rameters					
Parameter	Value		Unit			
V _{DS} @ T _{j,max}	850		V			
R _{DS(on),max}	0.9		Ω			
Q _{g,typ}	13		nC			
I _D	6		A			
I _{D,pulse}	18		А			
E _{oss} @ 400V	1.29		μJ			
Body Diode di _F /dt	500		A/µs			



Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted						
Parameter			Symbol	Values	Unit	
Continuous Drain Current	T _C = 25°C		- I _D	6		
	T _C = 100°C			3.6	A	
Pulsed Drain Current (note1		note1)	I _{D,pulse}	18	А	
Gate-Source Voltage			V_{GSS}	±30V	V	
Single Pulse Avalanche Energy (note2)		note2)	E _{AS}	62	mJ	
Repetitive Avalanche Energy (note2)		note2)	E _{AR}	0.21	mJ	
Avalanche Current			I _{AR}	1.3	А	
MOSFET dv/dt Ruggedness, V _{DS} = 0480V			dv/dt	50	V/ns	
Power Dissipation For TO-252, TO-251			P _D	63	W	
Continuous Diode Forward Current			I _S	5.1	Α	
Diode Pulsed Current (no		(note1)	I _{S,pulse}	18		
Reverse Diode dv/dt (note3)		(note3)	dv/dt	15	V/ns	
Maximum Diode Commutation Speed (note3)		(note3)	di _f /dt	500	A/µs	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55~+150	°C	

Thermal Resistance For TO-252,TO-251					
Parameter	Symbol	Value	Unit		
Thermal Resistance, Junction-to-Case	R _{thJC}	2.0	°C/W		
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62	C/W		

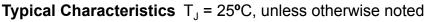


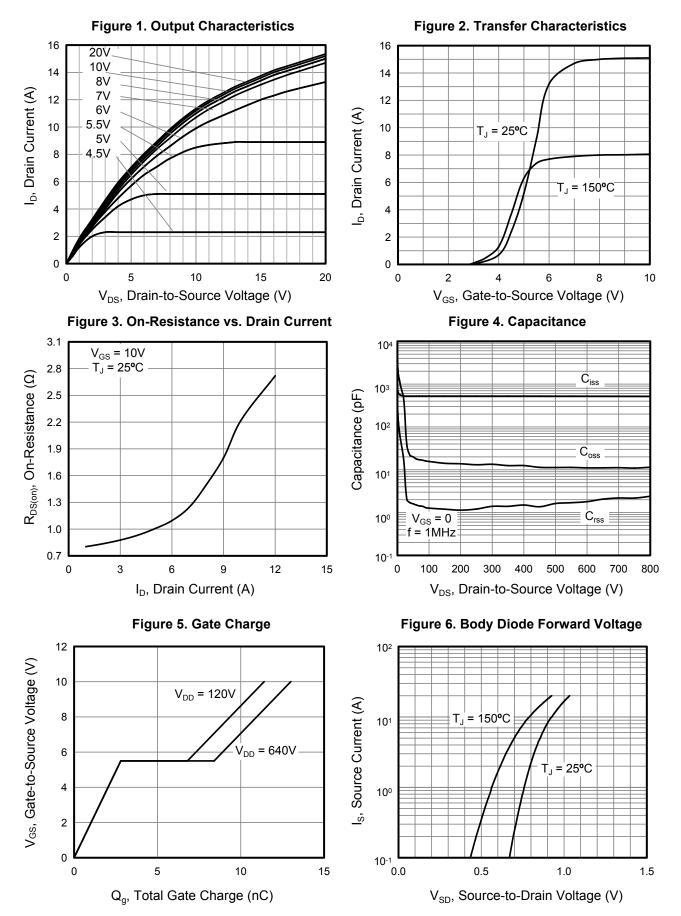
Electrical Characteristics $T_J = 25^{\circ}$ C, unless otherwise noted							
B			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0V, I _D = 250µA	800			V	
		V_{DS} = 800V, V_{GS} = 0V, T_{J} = 25°C			1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 800V, V_{GS} = 0V, T_{J} = 150°C			100	μA	
Gate-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2.5		4.5	V	
Drain-Source On-State-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3A		0.79	0.9	Ω	
Gate Resistance	R_{G}	f = 1.0MHz open drain		7.8		Ω	
Dynamic Characteristics							
Input Capacitance	C _{iss}	V _{GS} = 0V,		528.6			
Output Capacitance	C _{oss}	V _{DS} = 100V		16		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		0.31			
Total Gate Charge	Q _g	V _{DD} = 640V,		13			
Gate-Source Charge	Q_gs	I _D = 6A,		2.8		nC	
Gate-Drain Charge	Q_{gd}	V _{GS} = 10V		5.6			
Turn-on Delay Time	t _{d(on)}			41			
Turn-on Rise Time	t _r	$V_{DD} = 400V$		11			
Turn-off Delay Time	t _{d(off)}	$I_D = 6A$ $R_G = 25\Omega$		75		ns	
Turn-off Fall Time	t _f			37			
Drain-Source Body Diode Characte	ristics						
Body Diode Forward Voltage	V_{SD}	T_J = 25°C, I_{SD} = 3A, V_{GS} = 0V		0.9	1.2	V	
Reverse Recovery Time	t _{rr}	V _R = 400V		345		ns	
Reverse Recovery Charge	Q _{rr}	I _F = 6A		2.5		μC	
Peak Reverse Recovery Current	I _{rrm}	di _F /dt = 100A/µs		11.7		А	

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 3.5A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C
- 3. Identical low side and high side switch with identical ${\sf R}_{\sf G}$

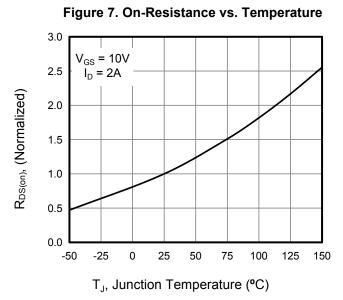




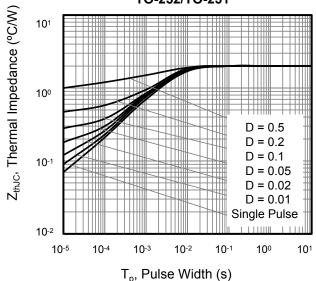




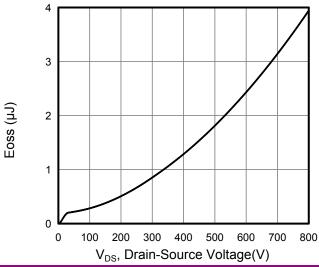
Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

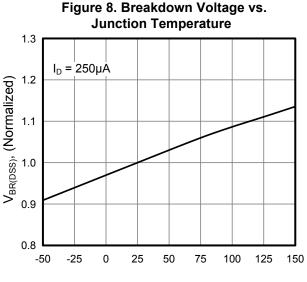






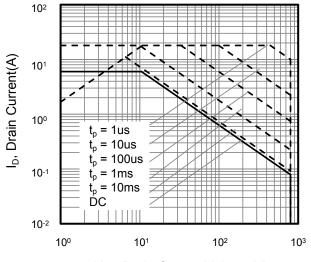






T_J, Junction Temperature (°C)

Figure 10. Safe Operation Area For TO-252/TO-251



V_{DS}, Drain-Source Voltage(V)



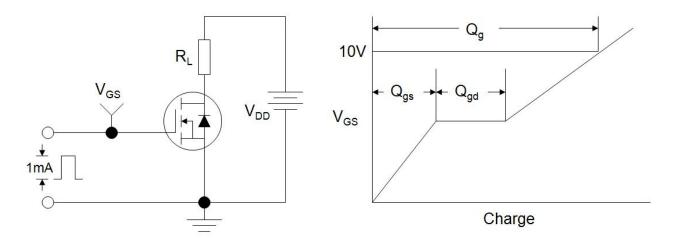


Figure B: Resistive Switching Test Circuit and Waveform

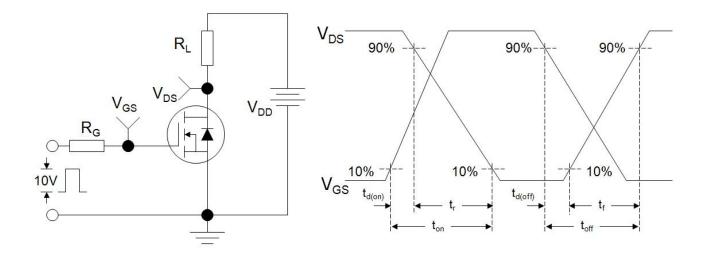
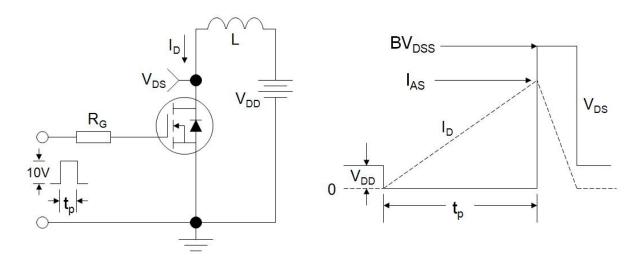
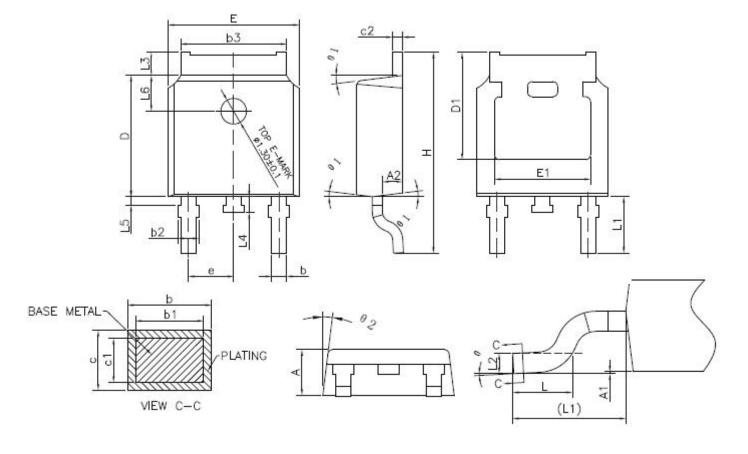


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-252(集佳)

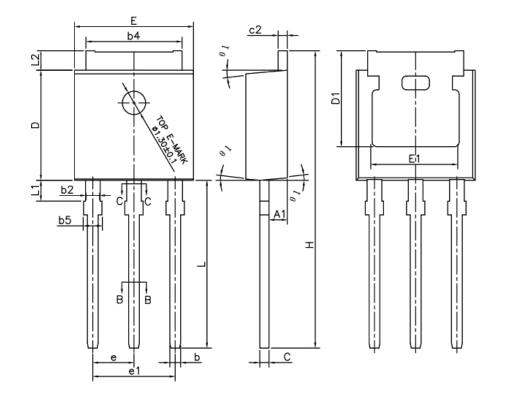


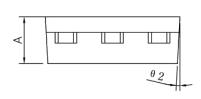
SYMBOL	MIN	NOM	MAX		
A	2,20	2,30	2,38		
A1	0		0,10		
A2	0,90	1,01	1,10		
b	0.72	- 10 - E	0.85		
b1	0.71	0.76	0.81		
b2	0.72	(1) <u> </u>	0.90		
b3	5.13	5.33	5.46		
c	0.47	- e r - 1 e - 8	0.60		
c1	0,46	0,51	0,56		
c2	0,47	22 2	0,60		
D	6,00	6,10	6,20		
D1	5,25	-67 <u>-1</u> 76 - §	(i <u>i</u> ii)		
E	6.50	6.60	6.70		
E1	4.70	2			
e	2.186	2.286	2,386		
н	9.80	10.10	10.40		
L	1,40	1,50	1,70		
L1	2,90 REF				
L2	0,508 BSC				
L3	0,90	33 <u></u> 33	1,25		
L4	0,60	0,80	1,00		
L5	0.15	3. 3	0.75		
L6	1.80 REF				
0	0°		8°		
01	5°	7º	9°		
92	5°	7°	9°		

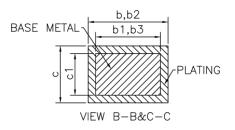
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TO-251 (集佳)







SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.35
A1	0.90	1.01	1.10
b	0.56		0.69
b1	0.55	0.60	0.65
b2	0.77		0.90
b3	0.76	0.81	0.86
b4	5.23	5.33	5.43
b5			1.05
С	0.46		0.59
c1	0.45	0.51	0.55
c2	0.46		0.59
D	6.00	6.10	6.20
D1	5.20		
E	6.50	6.60	6.70
E1	4.60	4.83	5.00
e	2.24	2.29	2.34
e1	4.47	4.57	4.67
Н	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.95	1.16	1.35
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°



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